

规格书编号：

SPEC NO：

产品规格书

SPECIFICATION

CUSTOMER 客户： _____
PRODUCT 产品： _____ SAW FILTER _____
MODEL NO 型号： _____ HDBF11508A64 SF6-4 _____
PREPARED 编制： _____ CHECKED 审核： _____
APPROVED 批准： _____ D A T E 日期： _____ 2009-8-19 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

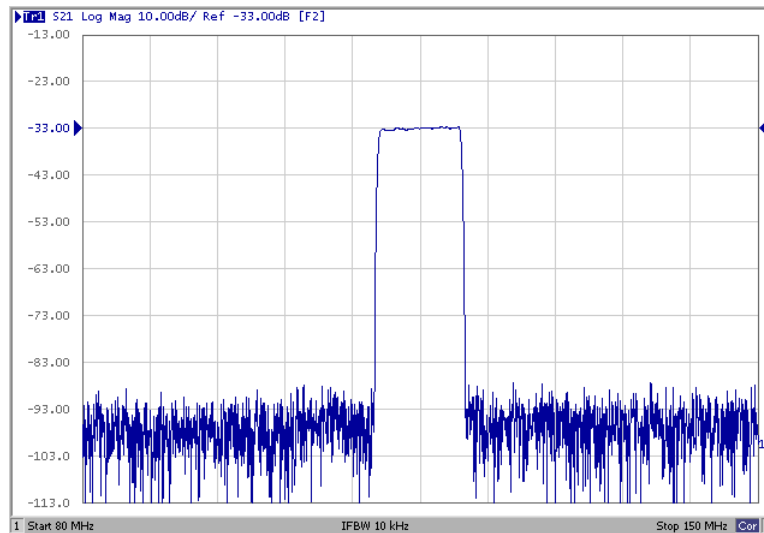
1. ELECTRICAL SPECIFICATION

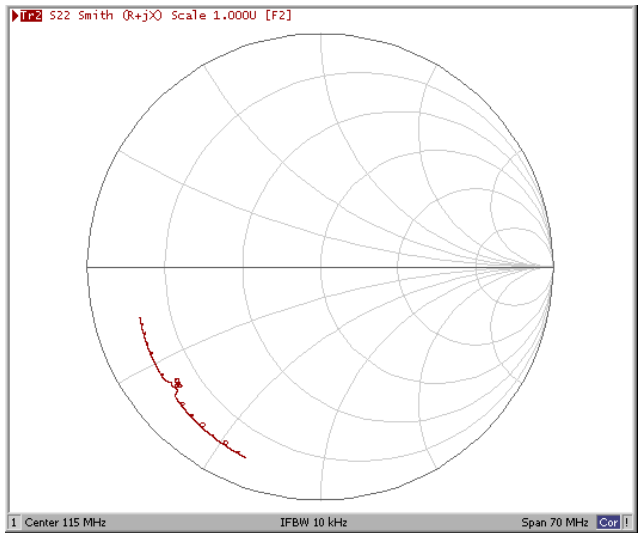
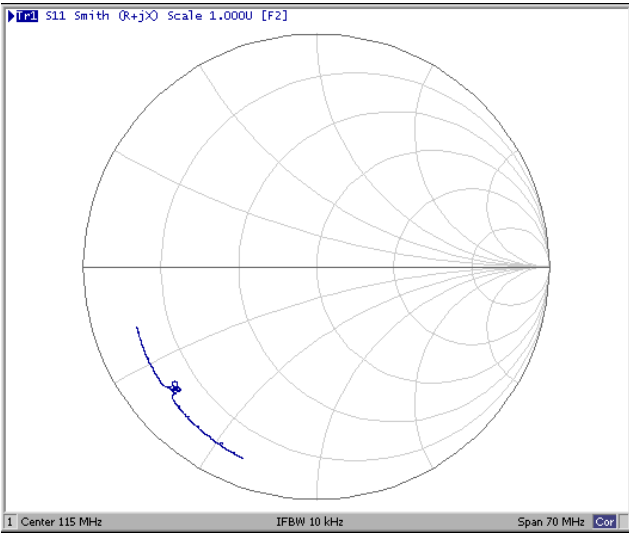
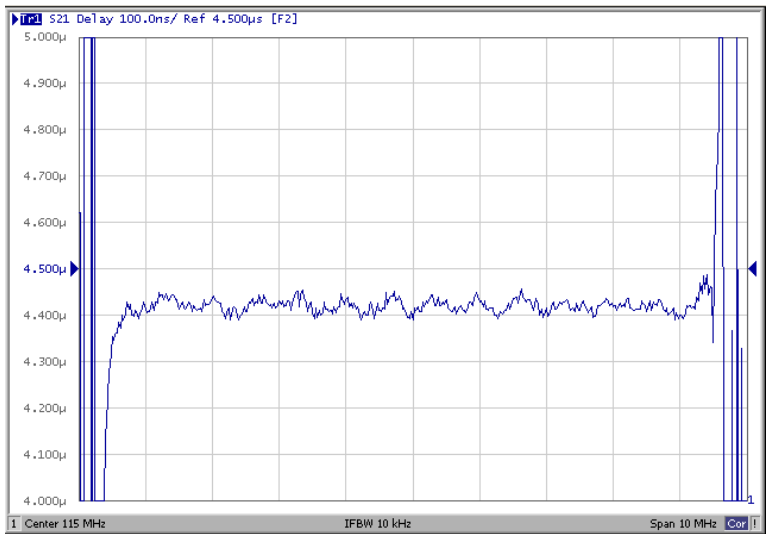
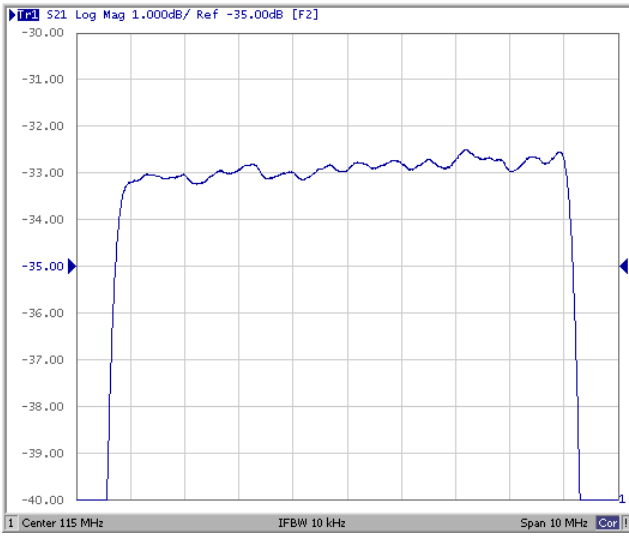
Maximum Input Power	+10dBm
DC voltage	0V
Storage Temperature Range	-45°C to +85°C
Operation Temperature Range	-40°C to +85°C

2.1 Electronic Characteristics

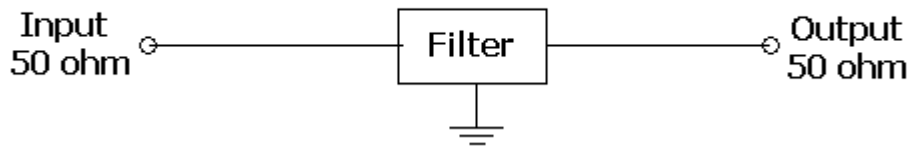
Parameter	Unit	Min	Type	Max
Center Frequency	MHz		115	
Insertion Loss	dB		33	35
-1.0dB Bandwidth	MHz	8.2	8.25	
-3dB Bandwidth	MHz		8.5	
-15dB Bandwidth	MHz		9.0	9.1
-40dB Bandwidth	MHz		9.3	9.5
Passband Variation	dB		1.0	2.0
Absolute delay	us		4.5	4.7
Ultimate Rejection	dB	50	55	
Material Temperature Coef	KHz/°C		2.6	
Ambient Temperature	°C		25	

2.2 Typical Frequency Response

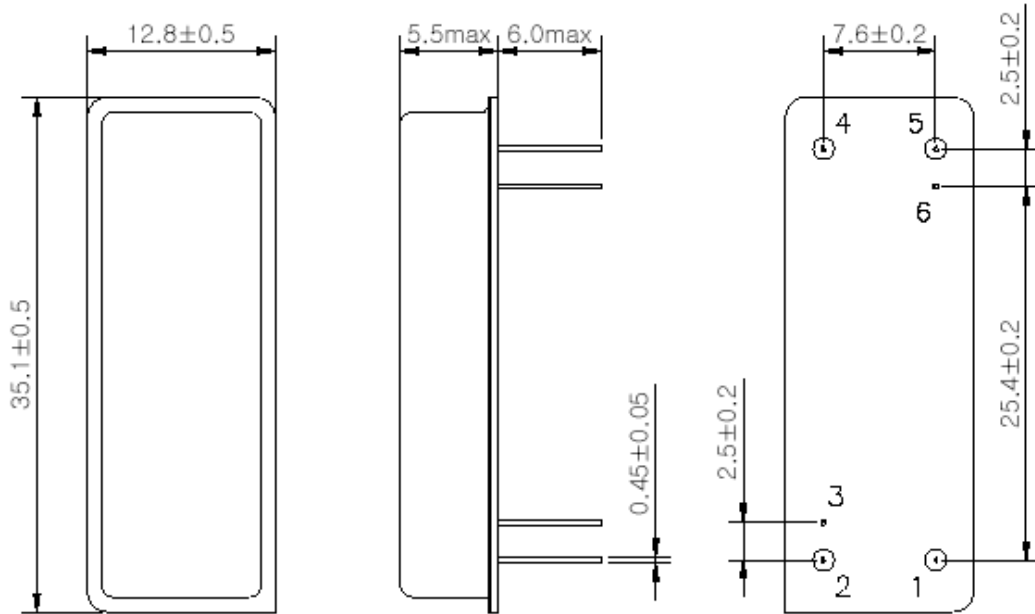




3. TEST CIRCUIT



4. DIMENSION



Pin Configuration	
1	Input
5	Output
2, 4	Ground
Other	Case ground

5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +25°C for 5 Minutes and a higher temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2.1.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260°C ±5°C for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.1.

5-3 Solderability

Submerge the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.1.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the

filter shall fulfill the specifications in 2.1.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2.1.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.